

**SEMICONDUCTOR DEVICE HAVING MULTI-CHIP
PACKAGE STRUCTURE**

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ABSTRACT

A semiconductor device having a multi-chip package structure and a manufacturing method therefor are provided. The semiconductor device includes a lead frame, a first integrated circuit chip, and a second integrated circuit chip. The first integrated circuit chip is attached to a top surface of the lead frame by a conductive adhesive, and the second integrated circuit chip is attached to a top surface of the first integrated circuit chip by an insulating adhesive tape or an insulation epoxy adhesive.